

In the Claims:

1-9. (Canceled)

10. (Currently Amended) The electronic module of claim ~~[[9]]~~20, wherein said at least one solder ball and said at least one pad are like in number.

11. (Original) The electronic module of claim 10, further comprising:

(d) for each said solder ball, and for a respective said pad, a respective wire operationally connecting said each solder ball to said respective pad.

12-14. (Canceled)

15. (Original) An electronic module, comprising:

- (a) electronic circuitry;
- (b) a first electrical connection mechanism, directly operationally connected to said electronic circuitry, for mounting of the electronic module by a first method; and
- (c) a second electrical connection mechanism, directly operationally connected to said electronic circuitry, for mounting of the electronic module by a second method different from said first method;

wherein mounting using only one of said connection mechanisms suffices to render the electronic module fully operational.

16. (Canceled)

17. (Original) An electronic module, comprising:
- (a) electronic circuitry;
 - (b) a first connection mechanism, operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by robotic mounting; and
 - (c) a second connection mechanism, operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by manual mounting;

wherein mounting using only said first connection mechanism suffices to render the electronic module fully operational; and wherein mounting using only said second connection mechanism suffices to render the electronic module fully operational.

18-19. (Canceled)

20. (Currently Amended) An electronic module, comprising:
- (a) electronic circuitry;
 - (b) a first connection mechanism, including at least one substantially hemispherical solder ball, and operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by a first method; and
 - (c) a second connection mechanism, including at least one electrically conducting pad, and operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by a second method different from said first method;

wherein mounting using only said first connection mechanism suffices to render the electronic module fully operational; and wherein mounting using only said second connection mechanism suffices to render the electronic module fully operational.

21. (Original) An electronic module, comprising:

- (a) electronic circuitry;
- (b) a first connection mechanism, operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by a first method; and
- (c) a second connection mechanism, including at least one electrically conducting pad, and operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by a second method different from said first method;

wherein mounting using only said first connection mechanism suffices to render the electronic module fully operational; and wherein mounting using only said second connection mechanism suffices to render the electronic module fully operational.

22. (Canceled)

23. (Original) An electronic module, comprising:

- (a) electronic circuitry;
- (b) a first connection mechanism, directly operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by a first method; and

- (c) a second connection mechanism, directly operationally connected to said electronic circuitry, for mounting of the electronic module on a printed circuit board by a second method different from said first method;

wherein mounting using only one of said connection mechanisms suffices to render the electronic module fully operational.